

ELECTRICAL REQUIREMENTS

Part Number	Inductance (μH)	Test Freq. (MHz)	R _{DC} (Ω) ±30%	Rated Current (mA) Max.	
				IDC*1	IDC*2
GMPI-252010-1R0MF1	1.0±20%	5	0.055	400	1600
GMPI-252010-1R5MF1	1.5±20%	5	0.07	700	1500
GMPI-252010-2R2MF1	2.2±20%	5	0.08	600	1300
GMPI-252010-3R3MF1	3.3±20%	5	0.1	350	1200
GMPI-252010-4R7MF1	4.7±20%	5	0.11	200	1100

●IDC*1 Inductance change should be less than ±30% when rated current is applied.

MEASURING METHOD / CONDITION

●Test Instrument:

L/SRF: Agilent 4291B Impedance Analyzer, Test Fixture: Agilent 16192

Osc. Level: 100mV

R_{DC}: Agilent 34401A

●Test Condition:

< Unless otherwise specified >

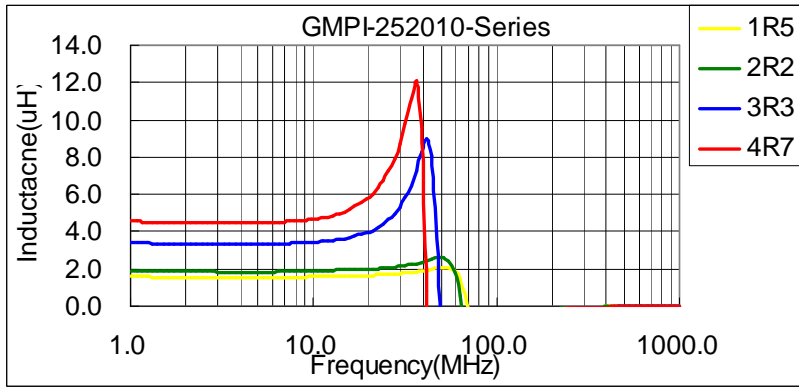
Temperature: 15°C to 35°C Humidity: 25% to 85% RH

< In case of doubt >

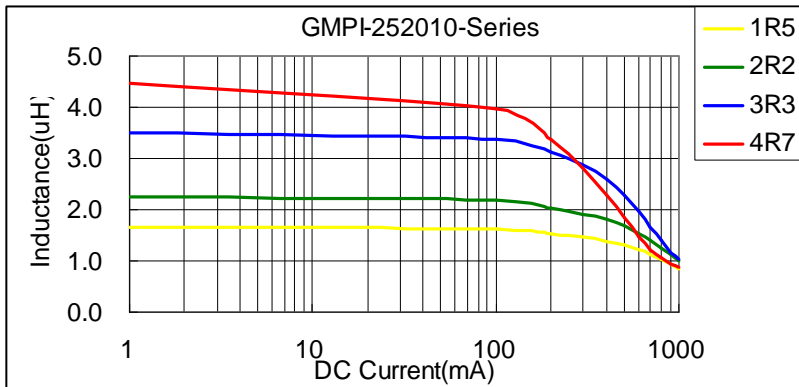
Temperature: 25°C ± 2°C Humidity: 60% to 70% RH



TYPICAL ELECTRICAL CHARACTERISTICS (T=25°C)

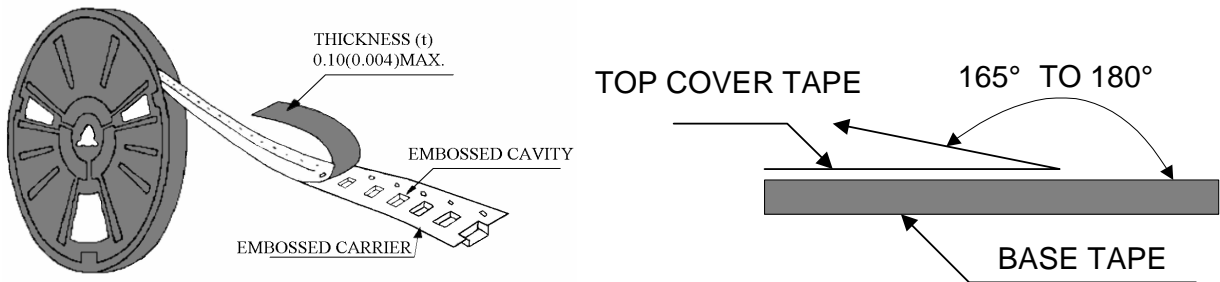


TYPICAL DC BIAS CHARACTERISTICS



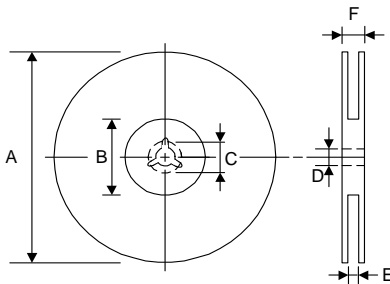
PACKAGING

● Peel-off Force

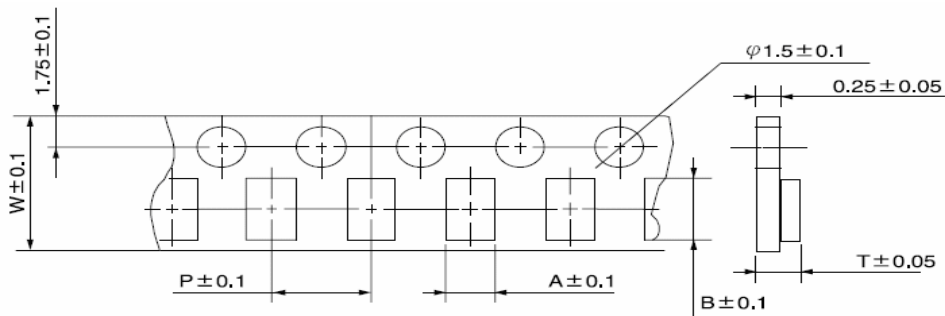


The force for peeling off cover tape is 10 grams in the arrow direction.

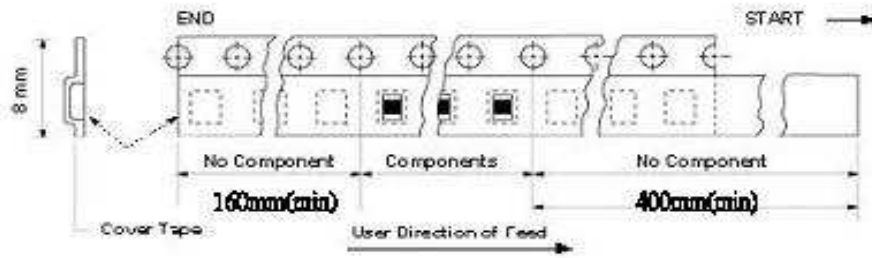
● Dimension (Unit: mm)



TYPE	A	B	C	D	E	F
8 mm	178±1	60 +0.5 -0	-	13 ±0.2	9 ±0.5	12 ±0.5
12 mm	178±0.3	60 ±0.2	19.3 ±0.1	13.5 ±0.1	13.6 ±0.1	-



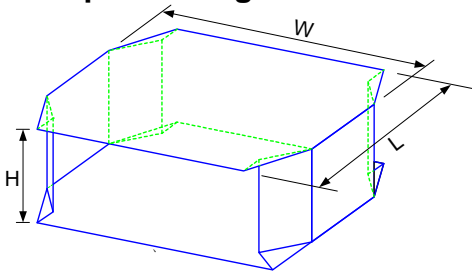
TYPE	SIZE	A	B	W	P	T	CHIPS/REEL
GMPI	252012	2.27	2.74	8	4	1.40	3000
GMPI	252010	2.20	2.90	8	4	1.20	3000
GMPI	201610	1.90	2.30	8	4	1.20	3000
GMPI	201209	1.42	2.25	8	4	1.00,	4000



● Taping Quantity

SERIES	PCS/Reel
252012	3000
252010	3000
201209	4000
201610	3000

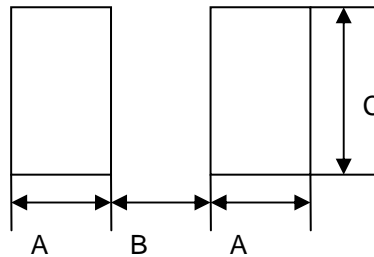
● Tape Packing Case



No. of Reels	W	L	H
2	18±0.5	18±0.5	2.4±0.2
3	18±0.5	18±0.5	3.6±0.2
4	18±0.5	18±0.5	4.8±0.2
5	18±0.5	18±0.5	6.0±0.2

Unit: cm

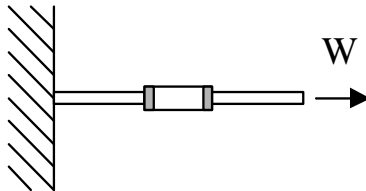
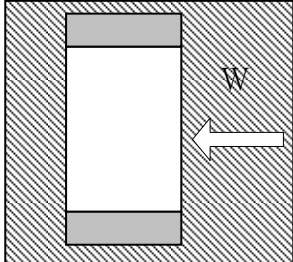
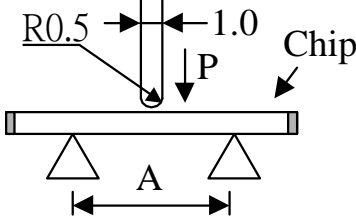
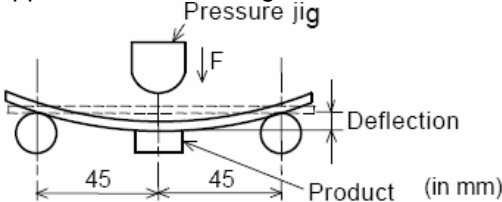
■ RECOMMENDED LAND PATTERNS



Unit: mm

Type	2520	2016	2012
A	0.8	0.7	0.7
B	1.2	0.8	0.8
C	2.2	1.8	1.45

RELIABILITY TEST

MECHANICAL PERFORMANCE TEST				
ITEM	SPECIFICATION	TEST CONDITION		
Solderability	More than 90% of the terminal electrode shall be covered with fresh solder.	Solder: Sn-3.0Ag-0.5Cu Solder Temperature: 245 ± 5°C Flux: Rosin Dip Time: 3 ± 1 Seconds		
Soldering Heat Resistance	The chip shall not crack. More than 75% of the terminal electrode shall be covered with solder.	Solder temperature : 260 ± 5°C Flux: Rosin Dip time: 10 ± 1 seconds		
Terminal Strength	The terminal electrode shall not be broken off nor the ferrite damaged. 	TYPE	W(KGF)	Time (Sec)
		GMPI-160808	0.6	30±5
		GMPI-201205	0.8	
		GMPI-201209	0.6	
		GMPI-201610	1.0	
		GMPI-252005	1.5	
		GMPI-252010	1.0	
		GMPI-252012		
		GMPI-321608		
		GMPI-322510		
GMPI-322512				
Terminal Strength	The terminal electrode shall not be broken off nor the ferrite damaged. 	TYPE	W(KGF)	Time (Sec)
		GMPI-160808	1.0	10±5
		GMPI-201205		
		GMPI-201209		
		GMPI-201610		
		GMPI-252005		
		GMPI-252010	2.0	
		GMPI-252012		
		GMPI-321608		
		GMPI-322510		
GMPI-322512				
Bending Strength	No mechanical damage. The ferrite shall not be damaged. 	TYPE	A(MM)	P(KGF)
		GMPI-160808	1.0	0.6
		GMPI-201205	1.4	1.0
		GMPI-201209		
		GMPI-201610		
		GMPI-252005	2.0	2.0
		GMPI-252010		1.0
		GMPI-252012		2.0
		GMPI-321608		
		GMPI-322510		
GMPI-322512				
Bending Test	Appearance: No damage Pressure jig 	Substrate:PCB(100mm×40mm×1.6mm) Solder: Reflow Speed of Applying Force: 0.5mm / s Deflection: 2mm Hold Duration: 30 s		

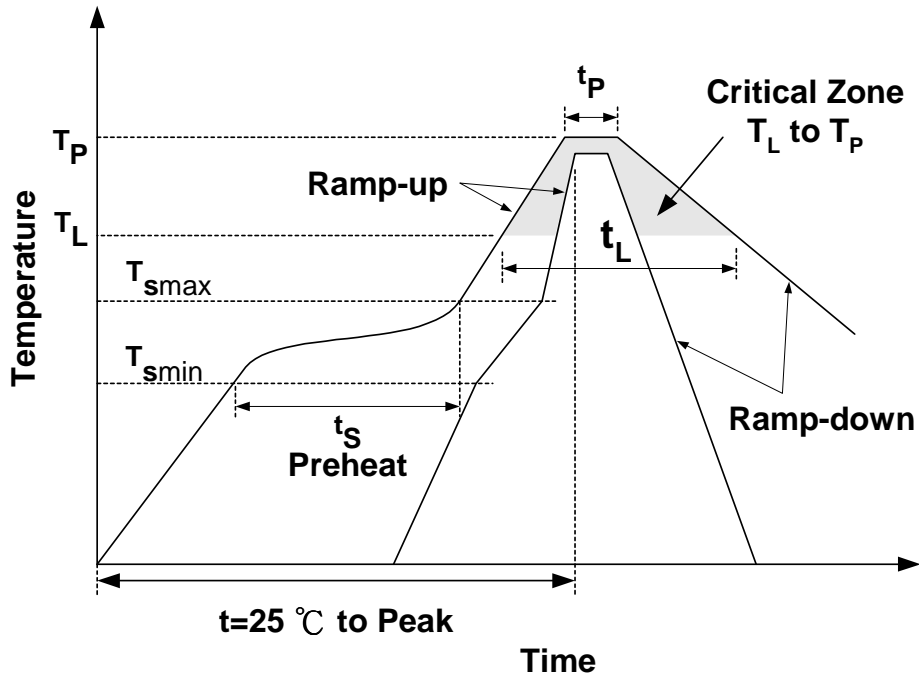
Vibration	$\Delta L/L_0 \leq \pm 5\%$ There shall be no mechanical damage.	The sample shall be soldered onto the printed circuit board and when a vibration having an amplitude of 1.52mm and a frequency of from 10 to 55Hz/1 minute repeated should be applied to the 3 directions (X,Y,Z) for 2 hours each.
Drop shock	No apparent damage	Dropped onto printed circuit board from 100cm height three times in x, y, z directions. The terminals shall be protected.

• CLIMATIC TEST

ITEM	SPECIFICATION	TEST CONDITION
Thermal Shock (Temperature Cycle)	No mechanical damage. Inductance shall be within $\pm 5\%$ of the initial value, and Q (shall be) within $\pm 30\%$ of the initial value.	Temperature: $-40^{\circ}\text{C}, 85^{\circ}\text{C}$ for 30 minutes each, 100 cycles.
Humidity Resistance		Temperature : 40°C Humidity: 95% RH Time: 1000 ± 12 HOURS
High Temperature Resistance		Temperature: $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ Time: 1000 ± 12 hours
Low Temperature Resistance		Temperature : $-40^{\circ}\text{C} \pm 2^{\circ}\text{C}$ Time: 1000 ± 12 hours

1. Operating Temperature Range: -55°C TO $+125^{\circ}\text{C}$
2. Storage Condition: The temperature should be within $-40^{\circ}\text{C} \sim 85^{\circ}\text{C}$ and humidity should be less than 75% RH. The product should be used within 6 months from the time of delivery.

RECOMMENDED REFLOW SOLDERING PROFILE



Profile Feature		Sn-Pb	Pb-Free
Preheat	t_s	60~120 seconds	60~180 seconds
	T_{smin}	100°C	150°C
	T_{smax}	150°C	200°C
Average ramp-up rate (T_{smax} to T_P)		3°C/second max.	3°C/second max.
Time main above	Temperature (T_L)	183°C	217°C
	Time (t_L)	60~150 seconds	60~150 seconds
Peak temperature (T_P)		230°C	250~260°C
Time within 5°C of actual peak temperature (t_p)		10 seconds	10 seconds
Ramp-down rate		6°C/sec max.	6°C/sec max.
Time 25°C to peak temperature		6 minutes max.	8 minutes max.

NOTES

The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.